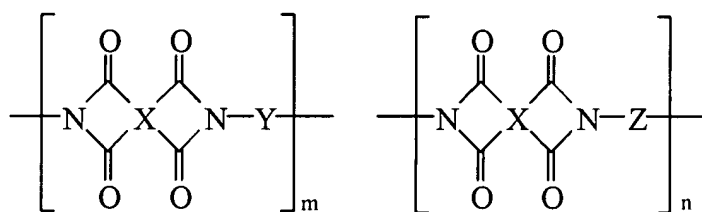


List of Claims

1. (Original) A polyimide resin comprising recurring units of the following structural formulae (1) and (2) and prepared using a diamine bearing an aromatic ring having an amino radical attached thereto and another aromatic ring having a phenolic hydroxyl radical so that the polyimide resin has phenolic hydroxyl radicals in its skeleton,

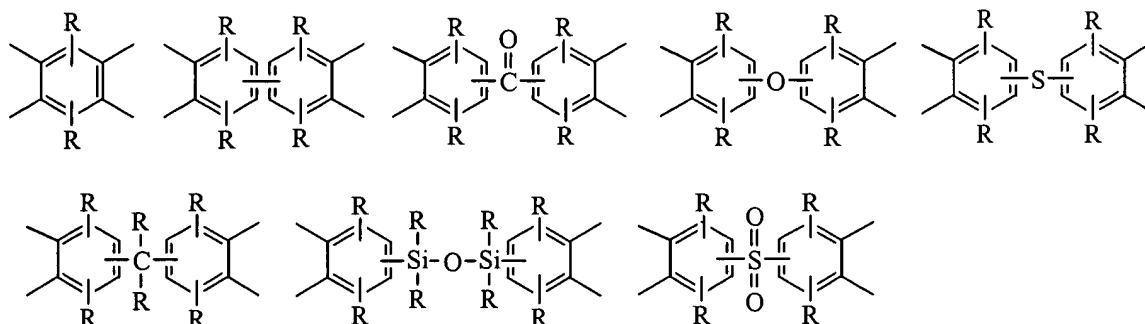


(1)

(2)

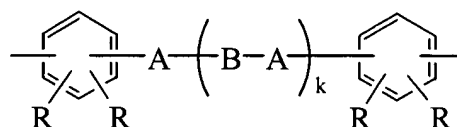
wherein X is at least one tetravalent organic radical selected from the group [I]; Y is a divalent organic radical comprising a diamine residue Y<sub>1</sub> having a phenolic hydroxyl radical represented by the formula [II] and an aromatic diamine residue Y<sub>2</sub> selected from the group [III]; Z is a siloxane diamine residue represented by the formula [IV]; Y<sub>1</sub>/(Y<sub>1</sub>+Y<sub>2</sub>) being from 0.01 to 1 in a molar ratio, m and n are natural numbers, satisfying 0.1 ≤ m/(m+n) ≤ 0.99 and 10 ≤ m+n ≤ 500,

Group (I)



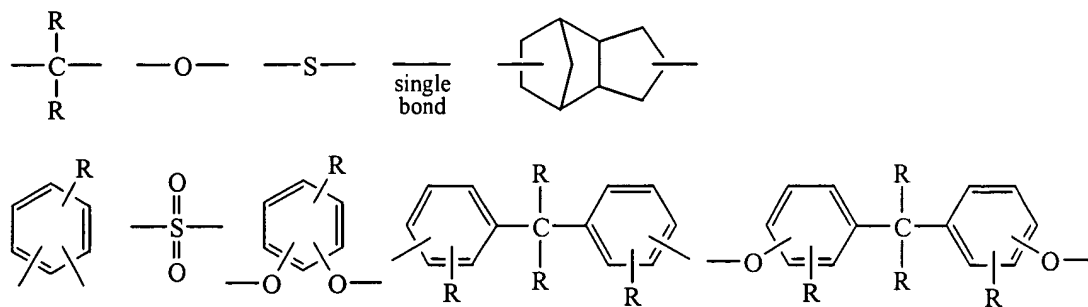
wherein R is independently a hydrogen atom, halogen atom or substituted or unsubstituted monovalent hydrocarbon radical of 1 to 8 carbon atoms,

Formula (II)

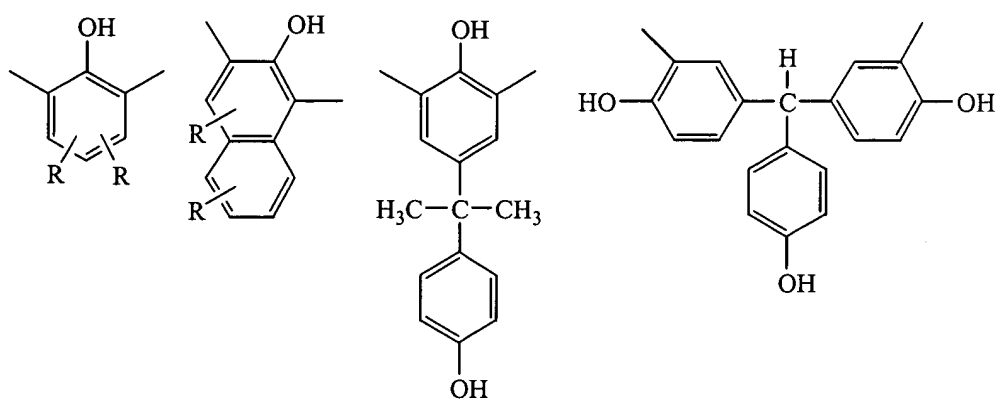


wherein A is a radical selected from the group [IIa] and B is a radical selected from the group [IIb]:

Group (IIa)

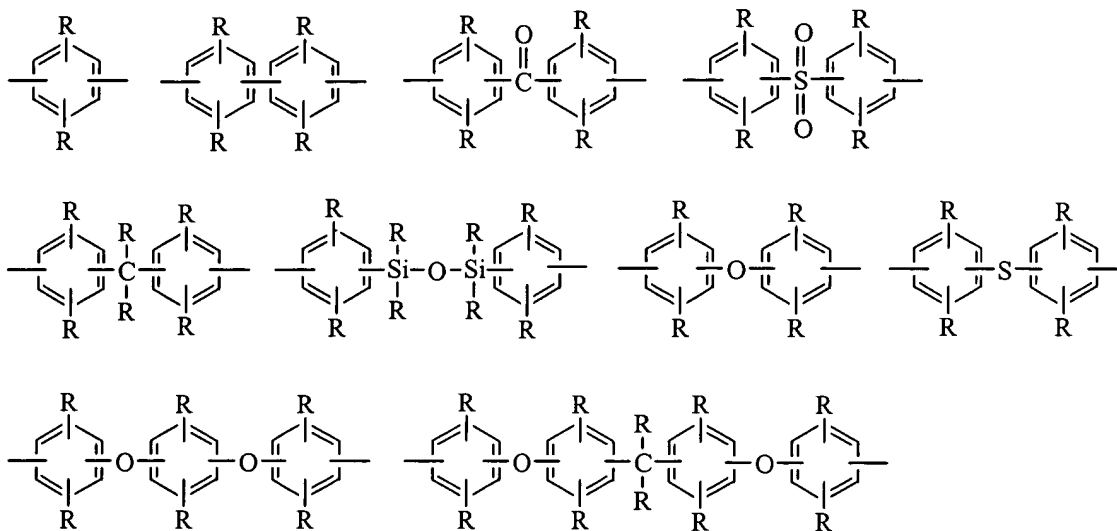


Group (IIb)



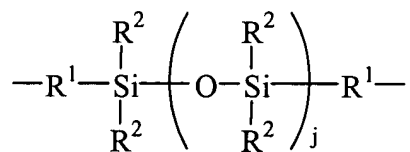
R is as defined above, and k is a natural number of 1 to 5,

## Group (III)



wherein R is as defined above,

## Formula (IV)



wherein R<sup>1</sup> is independently a C<sub>1-8</sub> alkylene or arylene radical, R<sup>2</sup> is independently a C<sub>1-8</sub> alkyl, alkoxy or aryl radical, and j is an integer of 4 to 60.

2. (Original) A method for preparing the polyimide resin of claim 1, comprising reacting a tetracarboxylic acid dianhydride having the general formula (3):



or its precursor, a tetracarboxylic acid or ester derivative thereof with diamines having the general formulae (4), (5) and (6):



wherein X, Y<sub>1</sub>, Y<sub>2</sub> and Z are as defined above, with the proviso that the amounts of diamines of formulae (4), (5) and (6) used are y<sub>1</sub> moles, y<sub>2</sub> moles and z moles, respectively, y<sub>1</sub>/(y<sub>1</sub>+y<sub>2</sub>) is from 0.01 to 1, and (y<sub>1</sub>+y<sub>2</sub>)/(y<sub>1</sub>+y<sub>2</sub>+z) is from 0.1 to 0.99, under such conditions as to give a molar ratio of P/Q > 1 wherein P is the amino radical on the diamine of formula (4) and Q is the acid anhydride residue (or 2 equivalents of carboxylic acid radical or ester radical) on the tetracarboxylic acid dianhydride of formula (3).

3. (Original) A polyimide resin composition comprising the polyimide resin of claim 1.

4. (Original) The polyimide resin composition of claim 3, further comprising an epoxy resin having at least two glycidyl radicals.

5. (Original) The polyimide resin composition of claim 4, further comprising an epoxy resin curing agent.

6. (NEW) The polyimide resin composition of claim 5, wherein the chemical equivalent ratio of the sum of the epoxy resin curing agent and the polyimide resin having phenolic hydroxyl radicals in its skeleton to the epoxy resin is in the range of between 0.7 and 1.3.

7. (NEW) The polyimide resin composition of claim 3, wherein the polyimide resin composition is dissolvable in an aprotic polar solvent.

8. (NEW) The polyimide resin composition of claim 7, wherein the solvent is cyclohexanone.

9. (NEW) A coating film comprising the polyimide resin composition of claim 3 coated to a substrate and wherein the coating film is adhesive to copper foil.